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(54) Title: TACTILE WAFER LIFTER AND METHODS FOR OPERATING THE SAME

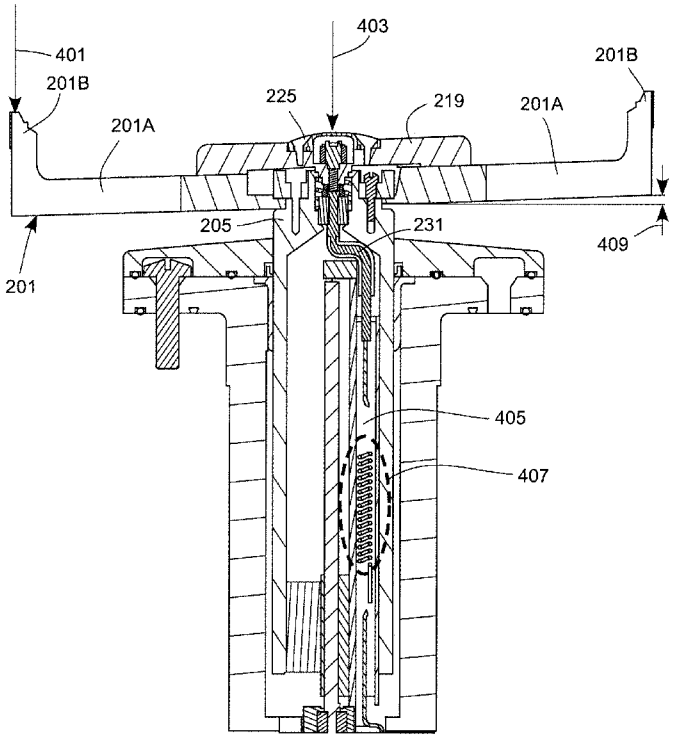


FIG. 4

(57) Abstract: A tactile wafer lifting apparatus includes a pedestal and a vertical drive connected to the pedestal. The vertical drive is defined to provide controlled upward and downward movement of the pedestal. The tactile wafer lifting apparatus also includes a wafer support member disposed over the pedestal. A tactile switch is disposed between the wafer support member and the pedestal such that sufficient downward force on the wafer support member causes activation of the tactile switch. The tactile switch is connected to the vertical drive so as to interrupt upward movement of the pedestal and wafer support member disposed thereover upon activation of the tactile switch.

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